

ABSTRACT OF THE DISCLOSURE

A semiconductor packaging substrate and a process for producing the same is disclosed. An internal circuit is formed by lamination. Then, external circuit is formed on the internal circuit by build-up technology. The substrate can be used as a flip-chip ball grid
5 array packaging substrate with high density and small pitch. Furthermore, the substrate of the invention has a plurality of bonding pads thereon. The bump pads are divided into power/ground bump pads, first signal bump pads, and second signal bump pads. The first signal bump pads surround the power/ground bump pads and are surrounded by the second signal bump pads.